

## EPOXY ADHESIVES SELECTING CHART

○ : Applicable    × : Not applicable

Product	Application	Remove		
		Solvent: SOLBULE B NIKKAEPORUN N	Hot Water	Heating
W-BOND	For semiconductor ingot slicing. High hardness and high adhesion type.	○	○	○
Q-BOND	Quick cure, high adhesion type which can be removed by hot water. Good for jig or large area mouting.	○	○	○
U-BOND	High adhering type for under 200 $\mu$ m slicing.Good for water-based slurry and can be used by auto dispensing and mounting machine.	○	○	○
B-BOND	Strong adhesion type for Metal jig and Glass type slicing beam, Easily removed both beams by heating after the process.	×	×	○

Please contact us for details as it may vary depending on the process conditions.

Please refer to SDS of each product for appropriate application and handling before use.